## **Complementary Power Transistors** For Isolated Package Applications

Designed for general-purpose amplifier and switching applications, where the mounting surface of the device is required to be electrically isolated from the heatsink or chassis.

#### Features

- Electrically Similar to the Popular MJE15030 and MJE15031
- 150 V<sub>CEO(sus)</sub>
- 8 A Rated Collector Current
- No Isolating Washers Required
- Reduced System Cost
- High Current Gain-Bandwidth Product
  - $f_T = 30 \text{ MHz} (\text{Min}) @ I_C$ 
    - = 500 mAdc
- UL Recognized, File #E69369, to 3500 V<sub>RMS</sub> Isolation
- Pb-Free Packages are Available\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	150	Vdc
Collector-Base Voltage	V <sub>CB</sub>	150	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	5	Vdc
$\begin{array}{l} RMS \mbox{ Isolation Voltage (Note 1)} \\ (t=0.3 \mbox{ sec, R.H.} \leq 30\%,  T_A = 25^{\circ}C) \\ Per \mbox{ Figure 11} \end{array}$	V <sub>ISOL</sub>	4500	V <sub>RMS</sub>
Collector Current – Continuous – Peak	Ι <sub>C</sub>	8 16	Adc
Base Current	Ι <sub>Β</sub>	2	Adc
Total Power Dissipation (Note 2) @ $T_C$ = 25°C Derate above 25°C	PD	36 0.016	W W/°C
Total Power Dissipation @ $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	PD	2.0 0.016	W W/°C
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta JC}$	3.5	°C/W
Lead Temperature for Soldering Purposes	ΤL	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Proper strike and creepage distance must be provided.

2. Measurement made with thermocouple contacting the bottom insulated surface (in a location beneath the die), the devices mounted on a heatsink with thermal grease and a mounting torque of  $\geq 6$  in. lbs.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



## **ON Semiconductor®**

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## COMPLEMENTARY SILICON POWER TRANSISTORS 8 AMPERES 150 VOLTS, 36 WATTS



INDE LOOSX	=	specific Device Code
		x = 0 or 1
G	=	Pb-Free Package
Α	=	Assembly Location
Y	=	Year
WW	=	Work Week

#### **ORDERING INFORMATION**

r		
Device	Package	Shipping
MJF15030	TO-220 FULLPACK	50 Units/Rail
MJF15030G	TO-220 FULLPACK (Pb-Free)	50 Units/Rail
MJF15031	TO-220 FULLPACK	50 Units/Rail
MJF15031G	TO–220 FULLPACK (Pb–Free)	50 Units/Rail

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS		•		•
Collector–Emitter Sustaining Voltage (Note 3) $(I_C = 10 \text{ mAdc}, I_B = 0)$	V <sub>CEO(sus)</sub>	150	-	Vdc
Collector Cutoff Current ( $V_{CE}$ = 150 Vdc, $I_B$ = 0)	I <sub>CEO</sub>	-	10	μAdc
Collector Cutoff Current ( $V_{CB} = 150 \text{ Vdc}, I_E = 0$ )	I <sub>CBO</sub>	-	10	μAdc
Emitter Cutoff Current ( $V_{BE} = 5 \text{ Vdc}, I_C = 0$ )	I <sub>EBO</sub>	-	10	μAdc
DN CHARACTERISTICS (Note 3)				
$ \begin{array}{l} \text{DC Current Gain} & (I_{C} = 0.1 \; \text{Adc},  V_{CE} = 2 \; \text{Vdc}) \\ & (I_{C} = 2 \; \text{Adc},  V_{CE} = 2 \; \text{Vdc}) \\ & (I_{C} = 3 \; \text{Adc},  V_{CE} = 2 \; \text{Vdc}) \\ & (I_{C} = 4 \; \text{Adc},  V_{CE} = 2 \; \text{Vdc}) \end{array} $	h <sub>FE</sub>	40 40 40 20	- - - -	_
			Тур	
DC Current Gain Linearity ( $V_{CE}$ from 2 V to 20 V, I <sub>C</sub> from 0.1 A to 3 A) (NPN to PNP)	h <sub>FE</sub>	2 3		
Collector-Emitter Saturation Voltage $(I_C = 1 \text{ Adc}, I_B = 0.1 \text{ Adc})$	V <sub>CE(sat)</sub>	-	0.5	Vdc
Base-Emitter On Voltage (I <sub>C</sub> = 1 Adc, V <sub>CE</sub> = 2 Vdc)	V <sub>BE(on)</sub>	_	1	Vdc
DYNAMIC CHARACTERISTICS		•	•	•
Current Gain – Bandwidth Product (Note 4)	f <sub>T</sub>	30	-	MHz

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

 $(I_C = 500 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f_{\text{test}} = 10 \text{ MHz})$ 

3. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2%.

4.  $f_T = |h_{fe}| \bullet f_{test}$ .







Figure 2. Forward Bias Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figures 2 and 3 is based on  $T_{J(pk)} = 150^{\circ}$ C;  $T_{C}$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} < 150^{\circ}$ C.  $T_{J(pk)}$  may be calculated from the data in Figure 1. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.





Figure 6. Current Gain — Bandwidth Product









0.5

 $I_{\rm C}/I_{\rm B} = 10$ 

10

5

2

1

IC, COLLECTOR CURRENT (AMP)

V<sub>BE(sat)</sub> @ I<sub>C</sub>/I<sub>B</sub> = 10

V<sub>CE(sat)</sub> @ I<sub>C</sub>/I<sub>B</sub> = 20

0.2

V<sub>BE(sat)</sub> @ I<sub>C</sub>/I<sub>B</sub> = 20



DC CURRENT GAIN

## **TEST CONDITIONS FOR ISOLATION TESTS\***

FULLY ISOLATED PACKAGE



Figure 11. Mounting Position

\*Measurement made between leads and heatsink with all leads shorted together.

## MOUNTING INFORMATION



Figure 12. Typical Mounting Techniques\*

Laboratory tests on a limited number of samples indicate, when using the screw and compression washer mounting technique, a screw torque of 6 to 8 in  $\cdot$  lbs is sufficient to provide maximum power dissipation capability. The compression washer helps to maintain a constant pressure on the package over time and during large temperature excursions.

Destructive laboratory tests show that using a hex head 4–40 screw, without washers, and applying a torque in excess of 20 in · lbs will cause the plastic to crack around the mounting hole, resulting in a loss of isolation capability.

Additional tests on slotted 4–40 screws indicate that the screw slot fails between 15 to 20 in  $\cdot$  lbs without adversely affecting the package. However, in order to positively ensure the package integrity of the fully isolated device, ON Semiconductor does not recommend exceeding 10 in  $\cdot$  lbs of mounting torque under any mounting conditions.

\*\* For more information about mounting power semiconductors see Application Note AN1040.

#### PACKAGE DIMENSIONS

TO-220 FULLPAK CASE 221D-03 **ISSUE J** 



NOTES 1. DIMENSIONING AND TOLERANCING PER ANSI

Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03. 3.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.617	0.635	15.67	16.12	
В	0.392	0.419	9.96	10.63	
C	0.177	0.193	4.50	4.90	
D	0.024	0.039	0.60	1.00	
F	0.116	0.129	2.95	3.28	
G	0.100 BSC		2.54 BSC		
Н	0.118	0.135	3.00	3.43	
J	0.018	0.025	0.45	0.63	
K	0.503	0.541	12.78	13.73	
L	0.048	0.058	1.23	1.47	
Ν	0.200 BSC		5.08 BSC		
Q	0.122	0.138	3.10	3.50	
R	0.099	0.117	2.51	2.96	
S	0.092	0.113	2.34	2.87	
U	0.239	0.271	6.06	6.88	

STYLE 2: PIN 1 BASE COLLECTOR 2. 3. EMITTER

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